XP04115

Silicon PNP epitaxial planar type

For digital circuits

Features

- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

Basic Part Number

• UNR2115 \times 2

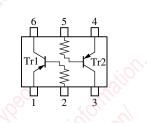
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter		Symbol	Symbol Rating	
Rating of	Collector-base voltage (Emitter open)	V _{CBO}	-50	V
element	Collector-emitter voltage (Base open)	V _{CEO}	-50	V
	Collector current	I _C	-100	mA
Overall	Total power dissipation	P _T	150	mW
	Junction temperature	Tj	150	°C
	Storage temperature	T _{stg}	-55 to +150	°C

Package

- Code
- SMini6-G1 • Pin Name
 - 1: Emitter (Tr1) 4: Emi
 - (Tr1) 4: Emitter (Tr2) r1) 5: Base (Tr2)
 - 2: Base (Tr1) 3: Collector (Tr2)
 - b) 6: Collector (Tr1)
- Marking Symbol: 6T

Internal Connection



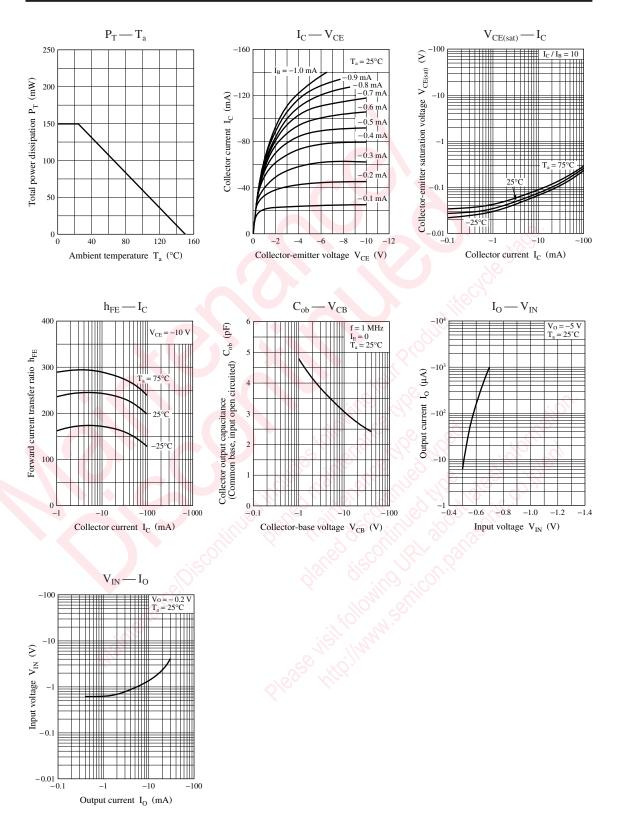
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Мах	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -50 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -50 \text{ V}, I_B = 0$			- 0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = -6 V, I_C = 0$			- 0.01	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$	160		460	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -0.3 \text{ mA}$			- 0.25	V
Output voltage high-level	V _{OH}	$V_{CC} = -5 V, V_B = -0.5 V, R_L = 1 k\Omega$	-4.9			V
Output voltage low-level	V _{OL}	$V_{CC} = -5 \text{ V}, \text{ V}_{B} = -2.5 \text{ V}, \text{ R}_{L} = 1 \text{ k}\Omega$			- 0.2	V
Input resistance	R ₁		-30%	10	+30%	kΩ
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

XP04115

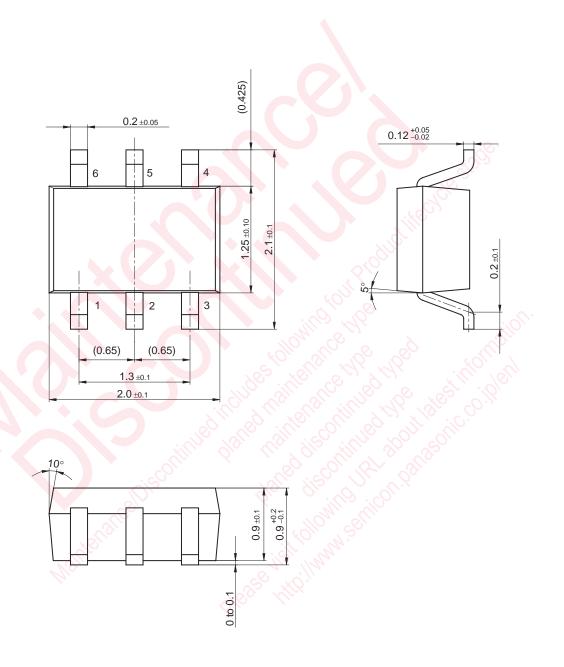




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SMini6-G1

Unit: mm



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